

## General Description

The MY3401A is the high cell density trenched P-CH MOSFET, which provide excellent  $R_{DS(ON)}$  and efficiency for most of the small power switching and load switch applications.

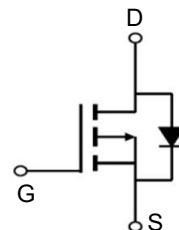
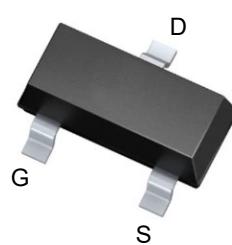


## Features

$V_{DSS}$	-30	V
$I_D$	-4.2	A
$R_{DS(ON)}(\text{at } V_{GS} = 10V)$	41	$\text{m}\Omega$
$R_{DS(ON)}(\text{at } V_{GS} = 4.5V)$	51	$\text{m}\Omega$

## Application

- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY3401A	SOT-23-3L	X1DA	3000

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D @ T_A=25^\circ\text{C}$	Continuous Drain Current	-4.5	A
$I_D @ T_A=70^\circ\text{C}$	Continuous Drain Current	-3.6	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-16	A
$P_D @ T_A=25^\circ\text{C}$	Total Power Dissipation <sup>3</sup>	1.4	W
$P_D @ T_A=70^\circ\text{C}$	Total Power Dissipation <sup>3</sup>	0.9	W
$T_{STG}$	Storage Temperature Range	-55 to 150	C
$T_J$	Operating Junction Temperature Range	-55 to 150	C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	105	C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup> ( $t \leq 10\text{s}$ )	---	---	C/W

**Electrical Characteristics (T<sub>j</sub>=25 °C, unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-30	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V	-	-	-1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ± 12V	-	-	± 100	nA
Gate-Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-0.7	-0.9	-1.3	V
Drain-Source on-Resistance <sup>3</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -4.2A	-	41	50	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -4A	-	51	61	
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -1A	-	64	80	
<b>Dynamic Characteristics<sup>4</sup></b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V, f = 1MHz	-	745	-	pF
Output Capacitance	C <sub>oss</sub>		-	70	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	57	-	
<b>Switching Characteristics<sup>4</sup></b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -15V, I <sub>D</sub> = -4.2A	-	8	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	1.8	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	2.7	-	
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>GS</sub> = -10V, V <sub>DD</sub> = -15V, I <sub>D</sub> = -4.2A, R <sub>GEN</sub> = 6Ω	-	7	-	ns
Rise Time	t <sub>r</sub>		-	3	-	
Turn-off Delay Time	t <sub>d(off)</sub>		-	30	-	
Fall Time	t <sub>f</sub>		-	12	-	
<b>Drain- Source Diode Characteristics</b>						
Diode Forward Voltage <sup>3</sup>	V <sub>SD</sub>	I <sub>S</sub> = -4.2A, V <sub>GS</sub> = 0V	-	-	-1.2	V
Continuous Source Current	I <sub>S</sub>				4.2	A

**Notes:**

1. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C
2. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
3. Pulse Test: Pulse width≤300μs, duty cycle≤2%.
4. This value is guaranteed by design hence it is not included in the production test.

### Typical Electrical and Thermal Characteristics

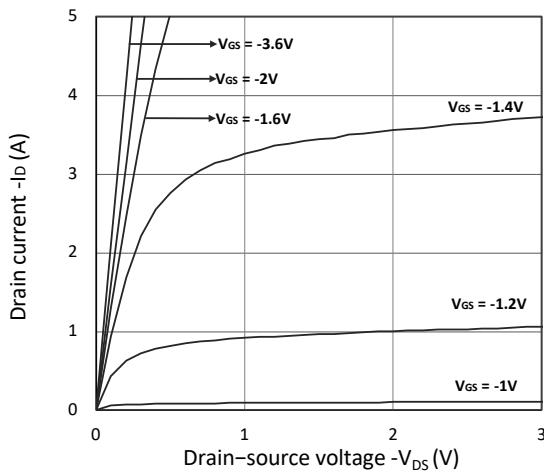


Figure 1. Output Characteristics

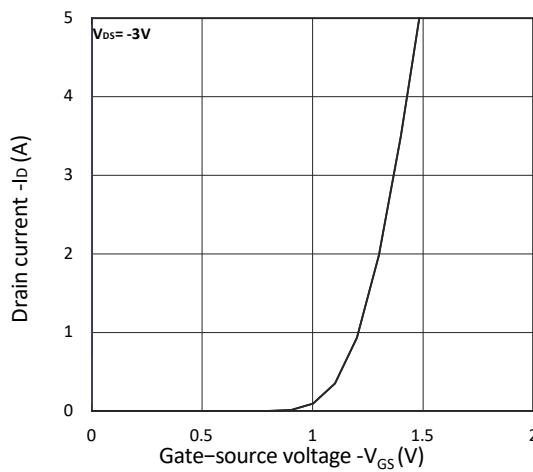


Figure 2. Transfer Characteristics

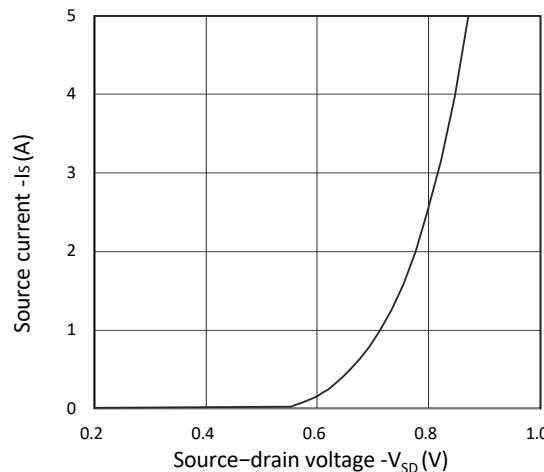


Figure 3. Forward Characteristics of Reverse

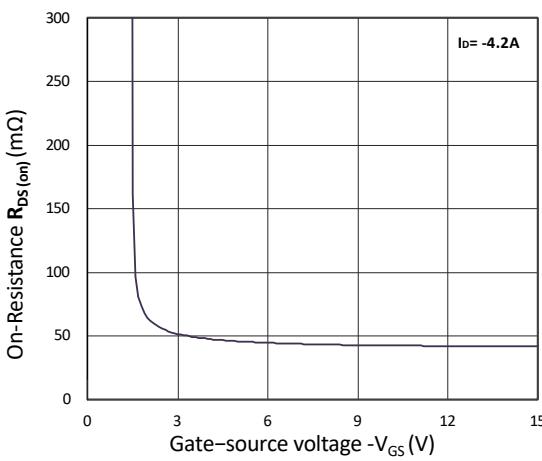


Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$

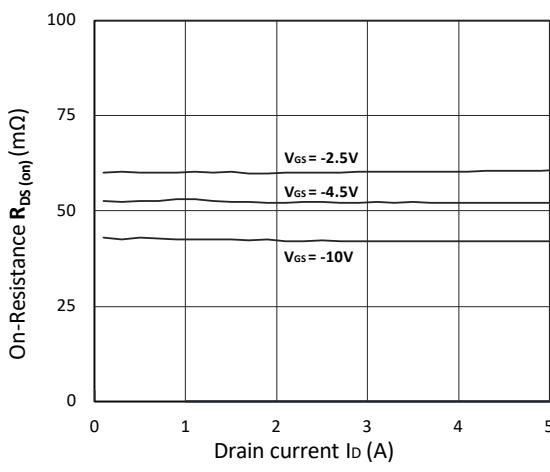


Figure 5.  $R_{DS(on)}$  vs.  $I_D$

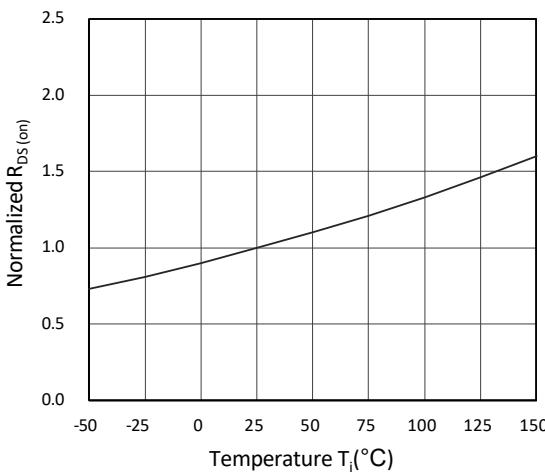


Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

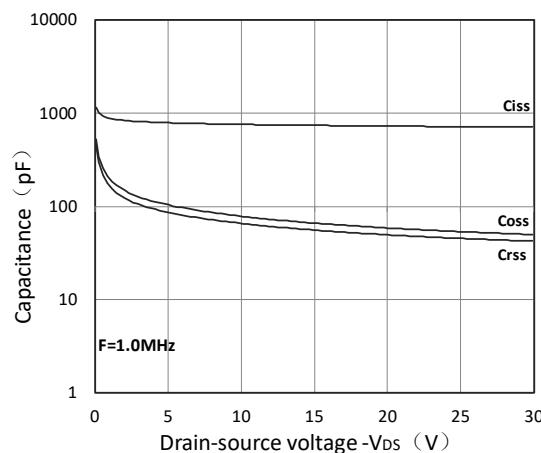


Figure 7. Capacitance Characteristics

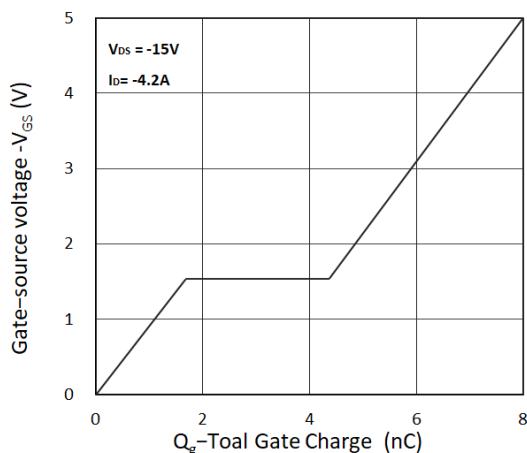


Figure 8. Gate Charge Characteristics

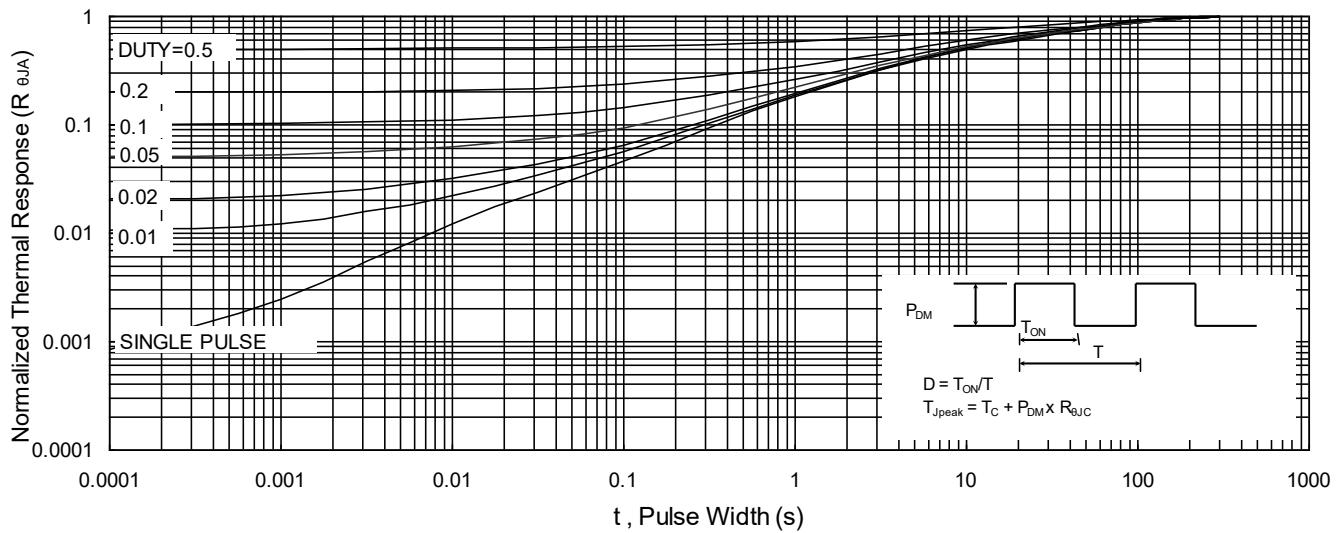


Fig.9 Normalized Maximum Transient Thermal Impedance

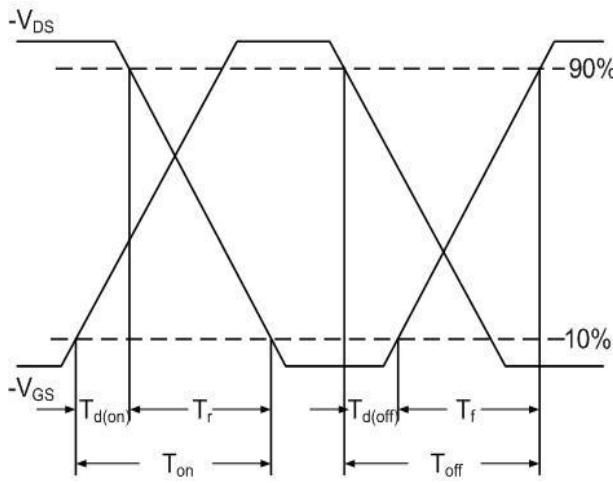


Fig.10 Switching Time Waveform

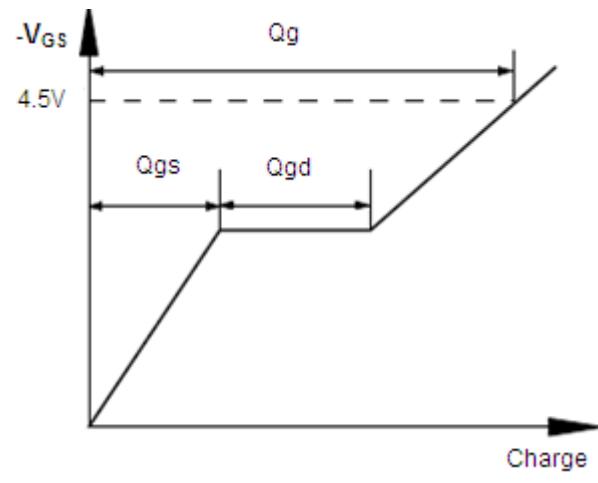
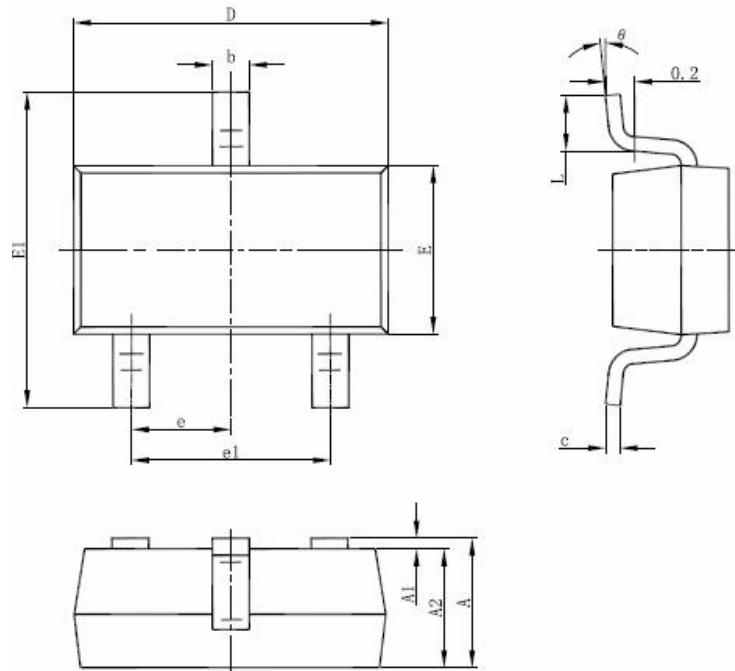


Fig.11 Gate Charge Waveform

**Package Mechanical Data-SOT-23-3L**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°